

## 1. General description

Silicon Carbide Schottky diode in a TSPAK plastic package, featured with top side cooling structure, designed for high frequency, high efficiency systems.



AEC - Q101 Qualified



## 2. Features and benefits

- Top side cooling structure
- New 6<sup>th</sup> Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability  $I_{FSM}$
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant
- AEC-Q101 qualified



## 3. Applications

- EV on board chargers
- EV DC-DC converters
- Other EV HV systems

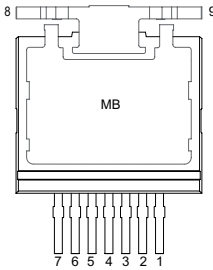
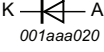
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		750			V
$I_F$	continuous forward current	$T_{mb} \leq 148\text{ °C}$ , DC; <a href="#">Fig. 2</a>	10			A
$T_j$	junction temperature		-55 to 175			°C
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 10\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 5</a>	-	1.29	1.45	V
		$I_F = 10\text{ A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 5</a>	-	1.45	1.65	V
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 10\text{ A}$ ; $di_F/dt = 500\text{ A}/\mu\text{s}$ ; $V_R = 400\text{ V}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>	-	24	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1-2	n.c	n.c		
3-7	A	anode		
8-9 mb	K	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WN6D10750TB-A	TSPAK	WN6D10750TB-A6Q	Reel	600	TSPAKH	06-Dec-2024

## 7. Marking

Table 4. Marking codes

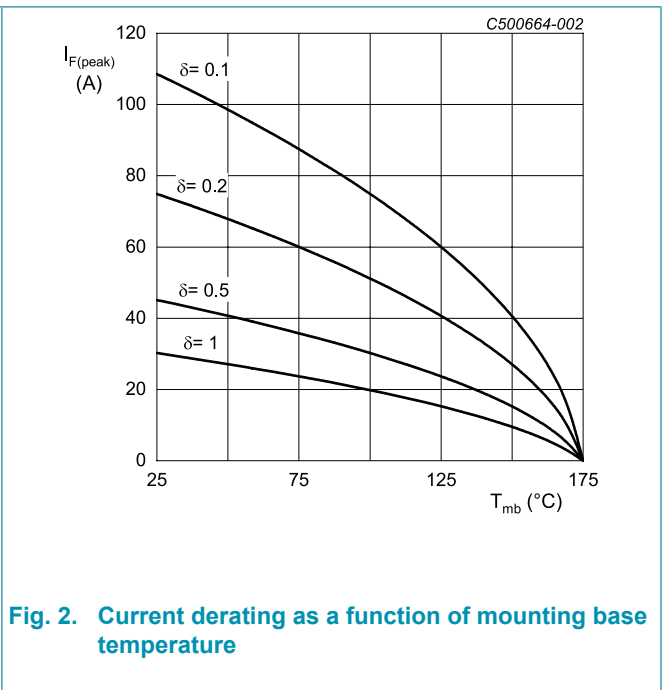
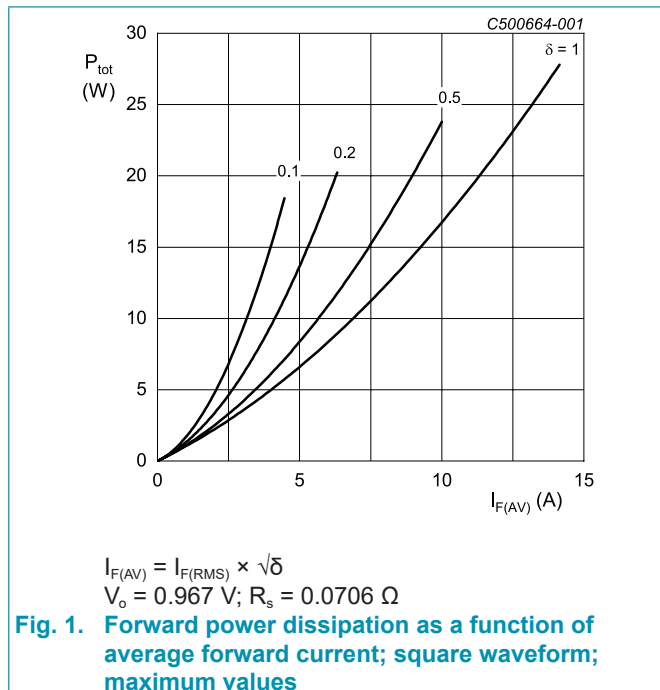
Type number	Marking codes
WN6D10750TB-A	WN6D 10750TB-A

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			750	V
$V_{RWM}$	crest working reverse voltage			750	V
$V_R$	reverse voltage	DC		750	V
$I_F$	continuous forward current	$T_{mb} \leq 148\text{ }^\circ\text{C}$ , DC; Fig. 2		10	A
		$T_{mb} \leq 125\text{ }^\circ\text{C}$ , DC; Fig. 2		16	A
		$T_{mb} \leq 25\text{ }^\circ\text{C}$ , DC; Fig. 2		30	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 125\text{ }^\circ\text{C}$ ; square-wave pulse		24	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse		65	A
		$t_p = 10\text{ }\mu\text{s}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; square-wave pulse		700	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; $t_p = 10\text{ ms}$		21.125	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature			-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature			-55 to 175	$^\circ\text{C}$



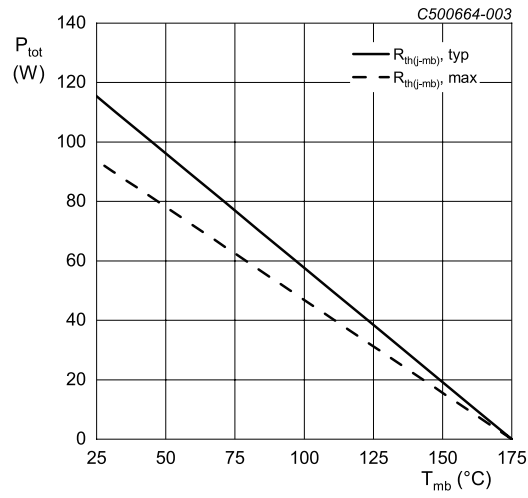


Fig. 3. Total power dissipation as a function of mounting base temperature

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 4</a>	-	1.3	1.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

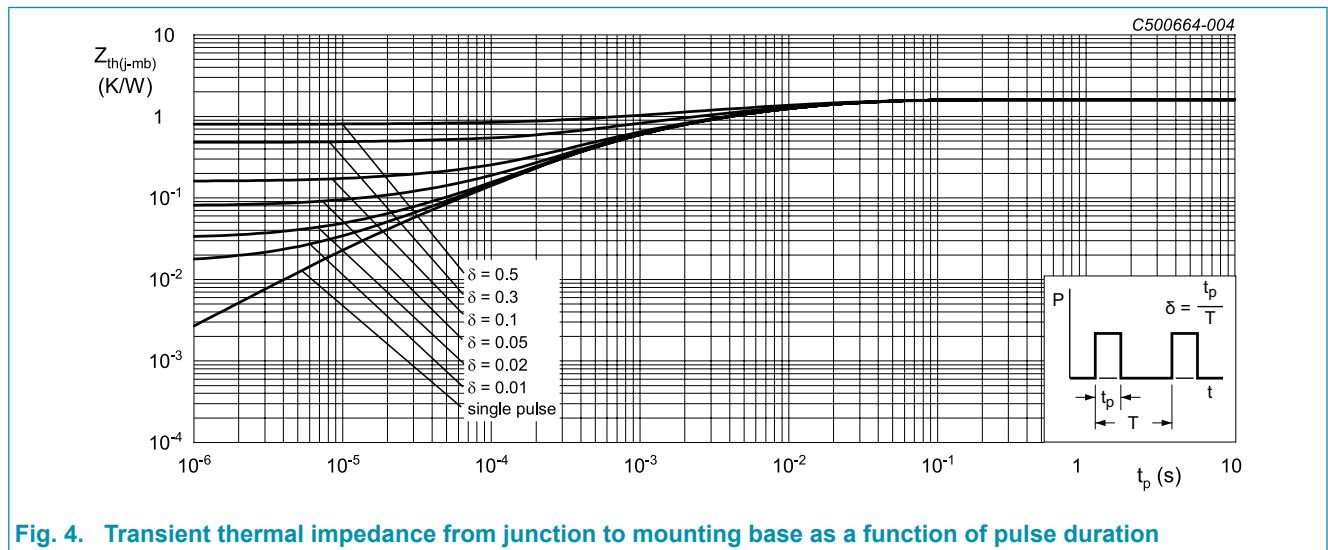
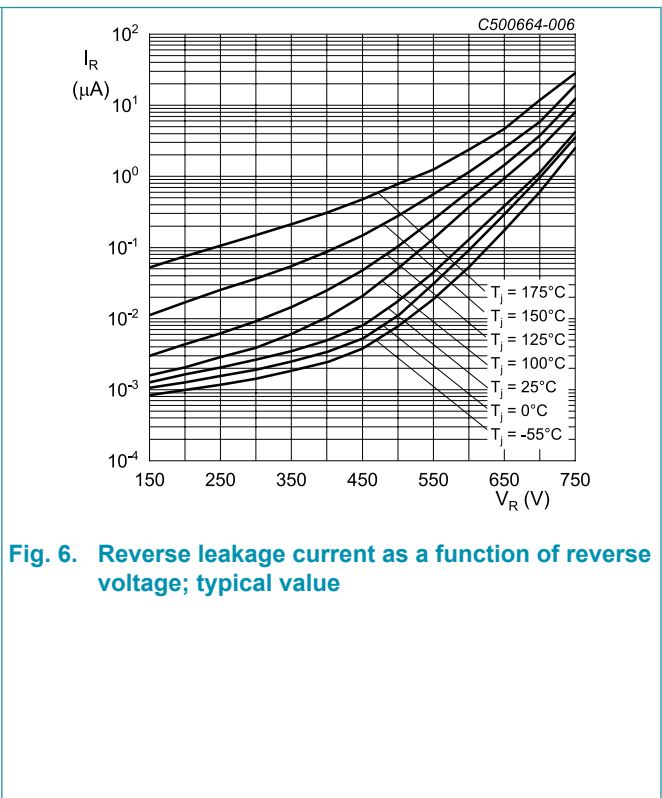
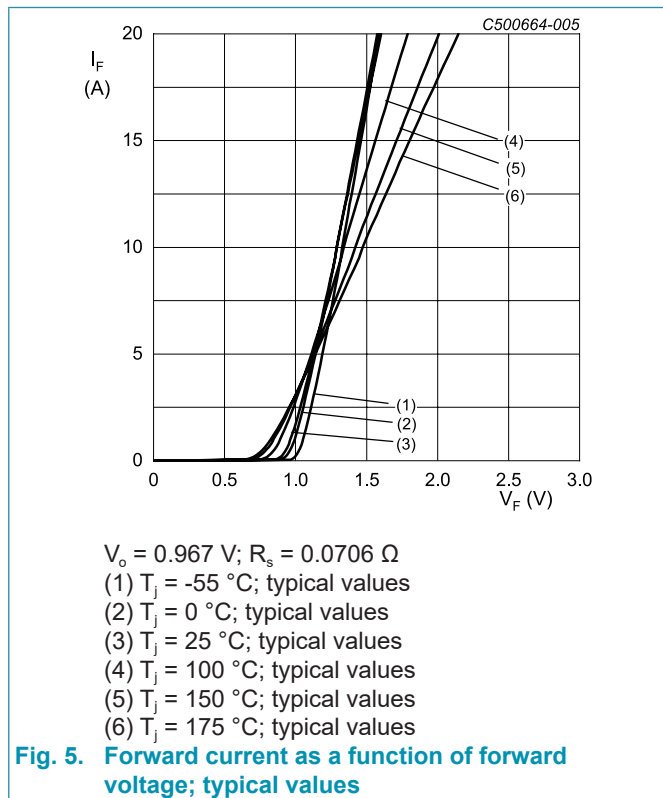


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 10\text{ A}; T_J = 25\text{ °C}; \text{Fig. 5}$	-	1.29	1.45	V
		$I_F = 10\text{ A}; T_J = 150\text{ °C}; \text{Fig. 5}$	-	1.45	1.65	V
		$I_F = 10\text{ A}; T_J = 175\text{ °C}; \text{Fig. 5}$	-	1.50	1.70	V
$I_R$	reverse current	$V_R = 750\text{ V}; T_J = 25\text{ °C}; \text{Fig. 6}$	-	1	50	$\mu\text{A}$
		$V_R = 750\text{ V}; T_J = 175\text{ °C}; \text{Fig. 6}$	-	15	200	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 10\text{ A}; V_R = 400\text{ V}; di_F/dt = 500\text{ A}/\mu\text{s}; T_J = 25\text{ °C}; \text{Fig. 7}$	-	24	-	nC
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 1\text{ V}; T_J = 25\text{ °C}$	-	500	-	pF
		$f = 1\text{ MHz}; V_R = 300\text{ V}; T_J = 25\text{ °C}$	-	58	-	pF
		$f = 1\text{ MHz}; V_R = 600\text{ V}; T_J = 25\text{ °C}$	-	52	-	pF
$E_{as}$	non-repetitive avalanche energy	$I_R = 5\text{ A}; L = 5\text{ mH}; T_{J(\text{init})} = 25\text{ °C}$	60	-	-	mJ



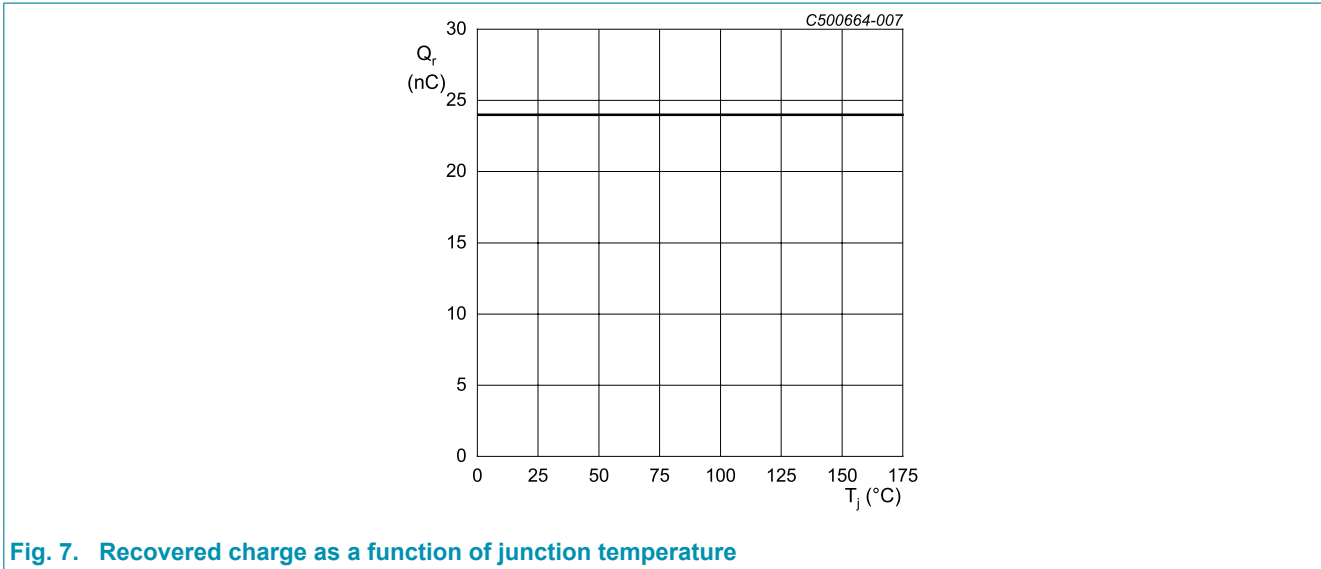
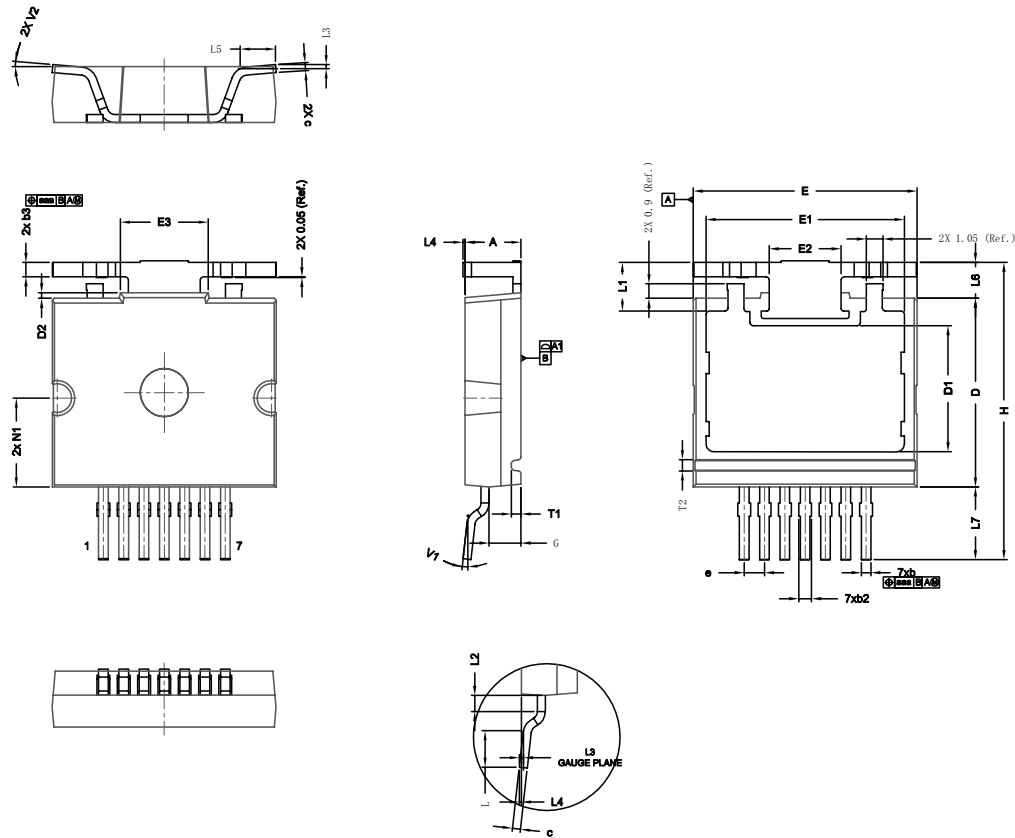
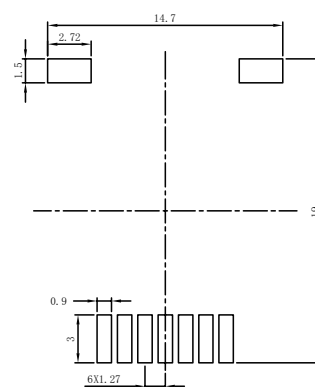


Fig. 7. Recovered charge as a function of junction temperature

### 11. Package outline



SYMBOL	DIMENSIONS MILLIMETER			SYMBOL	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.
A	3.40	3.50	3.60	H	18.00	18.58	19.00
A1	0.05			L	2.185	2.285	2.385
b	0.50	0.60	0.70	L1	3.04		
b2	0.70	0.80	0.90	L2	0.90	1.00	1.10
b3	0.80	0.90	0.98	L3	0.26		
c	0.40	0.50	0.60	L4	0.075	0.125	0.175
D	11.70	11.80	11.90	L5	2.10	2.20	2.30
D1	7.78	7.88	7.98	L6	2.14	2.24	2.34
D2	0.24	0.34	0.44	L7	4.44	4.54	4.64
E	13.90	14.00	14.10	N1	5.46	5.56	5.66
E1	12.30	12.40	12.50	T1	0.6(Ref)		
E2	4.45	4.50	4.55	T2	0.7(Ref)		
E3	5.45	5.50	5.55	V1	0°		8°
e	1.27			V2	0°		8°
G	1.90	2.00	2.10	aaa	0.1		



Footprint(Only for reference)

- NOTES.
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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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